To the Honorable Commission Patents and Trademarks: Please record the attached orig document or copy thereof.



1. Name of party or parties conveying an	2. Name and address of party or parties
interest:	receiving an interest:
Sang Hun Oh 2. 13.0 U	Name: ANAM Semiconductor, Inc. 891-10 Daechi-dong, Gangnam-gu Seoul, Republic of Korea
3. Description of the interest conveyed:	Other:
X Assignment	OPR/FINANCE
Merger	न्न हो
Change of Name	7 7
Security Agreement	
<u> </u>	The state of the s
Execution Date: January 26, 2004	7: 2°
4. Application number(s) or patent number(s).	If the document is being filed together with a
Additional sheet attached? YES NO_X	new application, the execution date of the application is:
TES NO_X	application is.
A. Patent Application no.(s): 10/764,905 filed January 26, 2004	B. Patent no.(s):
5. Name and address of party to whom	6. Number of applications and/or patents
correspondence concerning this cover sheet	identified on this cover sheet: 1
should be mailed:	
Name: James A. Flight	7. Amount of fee enclosed or authorized to b
Reg. No. 37,622	charged: \$40.00
GROSSMAN & FLIGHT, LLC Street Address: 20 North Wacker Drive	540.00
Suite 4220	8. Any additional required fee may be charge
City: Chicago	or any overpayment credited to our deposit
State: Illinois	account: 50-2455
Zip: 60606	
<u> </u>	he information dontained on this cover sheet is
and correct and any copy submitted is a true copy	of the original document.
Date: February 10, 2004	Van le this MA
Date. 1 cornary 10, 2007	James A. Flight Registration No. 37 632
Total number of pages including cover sh	Registration No. 37,622 eet, attachments, and document: 3
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PATENT REEL: 014975 FRAME: 0508

## ASSIGNMENT

Serial No: 10/764,905

Filed: January 26, 2004

Title:

METHODS FOR FORMING AN AIR GAP IN A SEMICONDUCTOR

METAL LINE MANUFACTURING PROCESS

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assigns to ANAM Semiconductor, Inc., (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other applications, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrants himself to be the owner of the interest herein assigned and to have the right to make this assignment and further warrants that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, that said assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further agrees upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of

REEL: 014975 FRAME: 0509

the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date: January 26, 2004

**RECORDED: 02/13/2004** 

Signature

Name

Sang Hun Oh Sang Hun Oh

\* \* \* \*

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